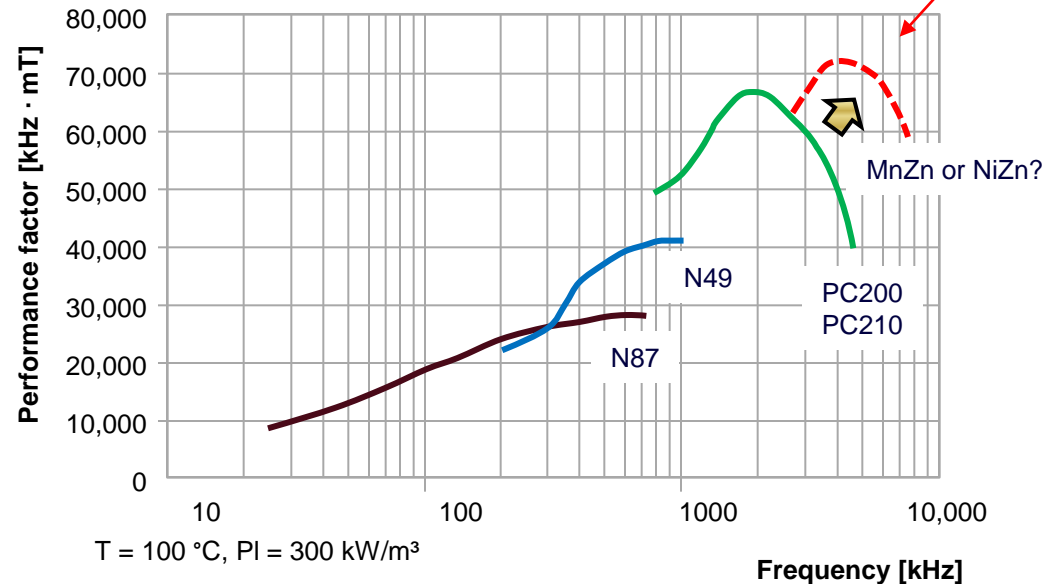


New TDK high frequency Mn-Zn FER materials

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Šumperk, Czech Republic
March 17, 2017

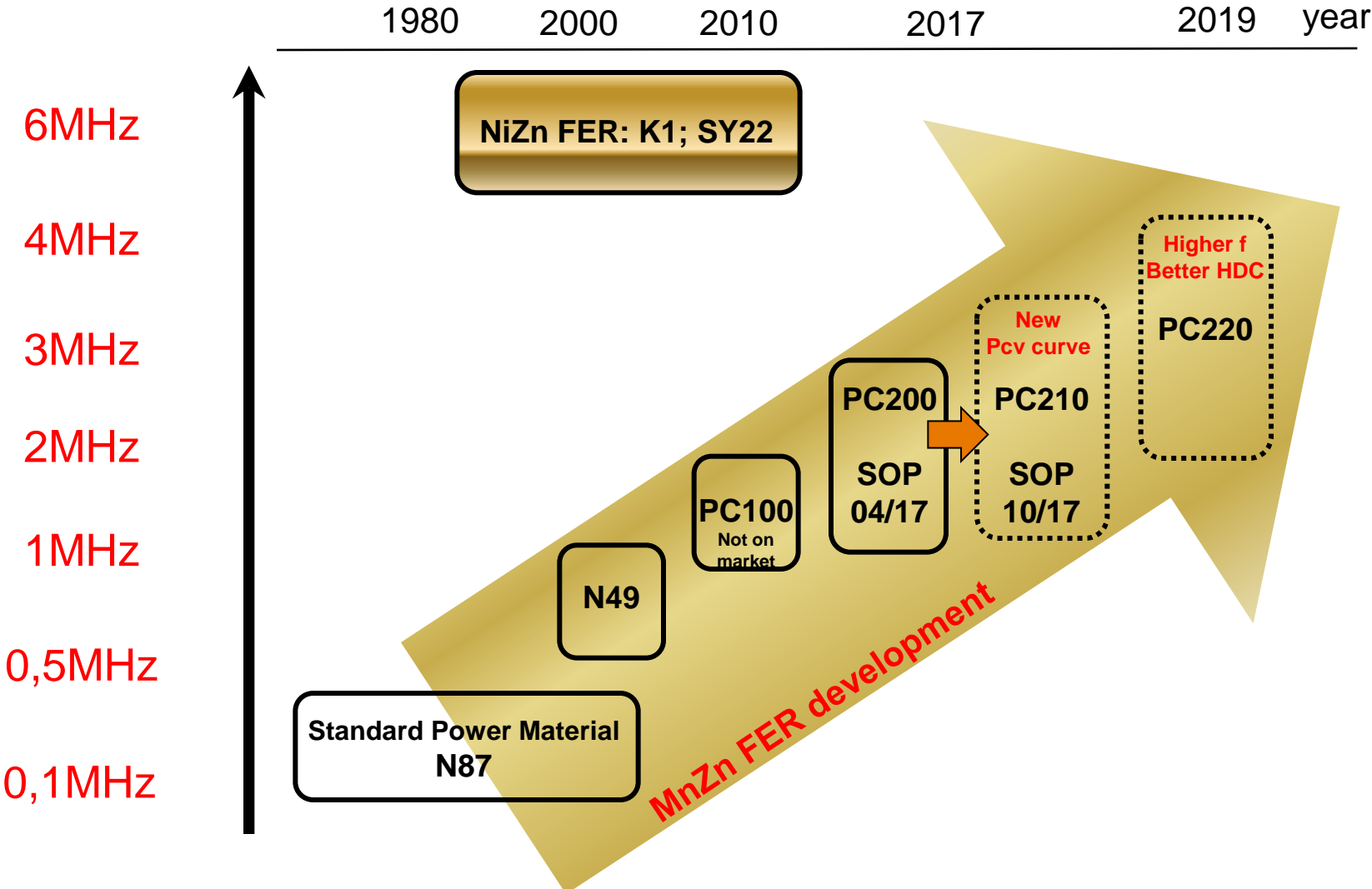
New materials – High frequency



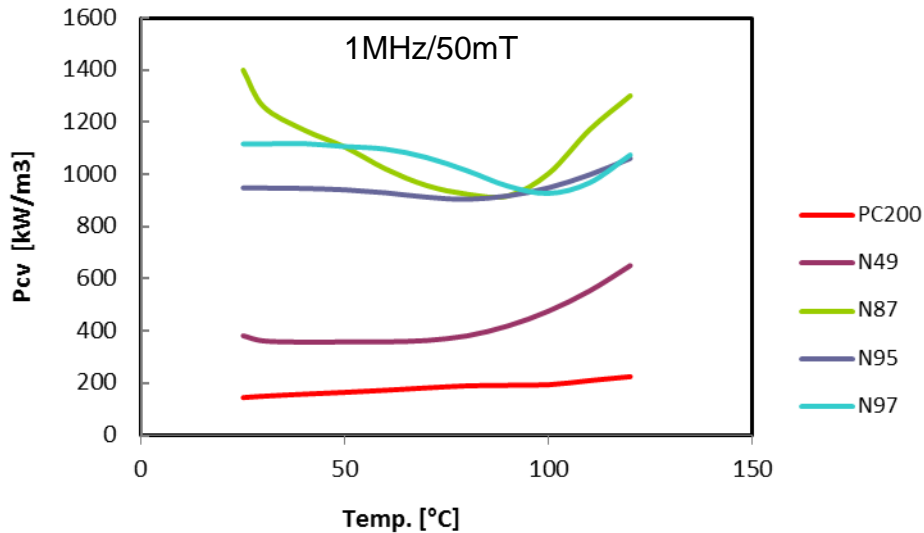
- Higher switching $f \Rightarrow$ compact core shape
- Lower PI at high $f \Rightarrow$ higher efficiency, lower heat rise

Target: Increase power density by using higher switching frequencies.

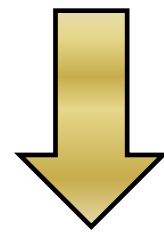
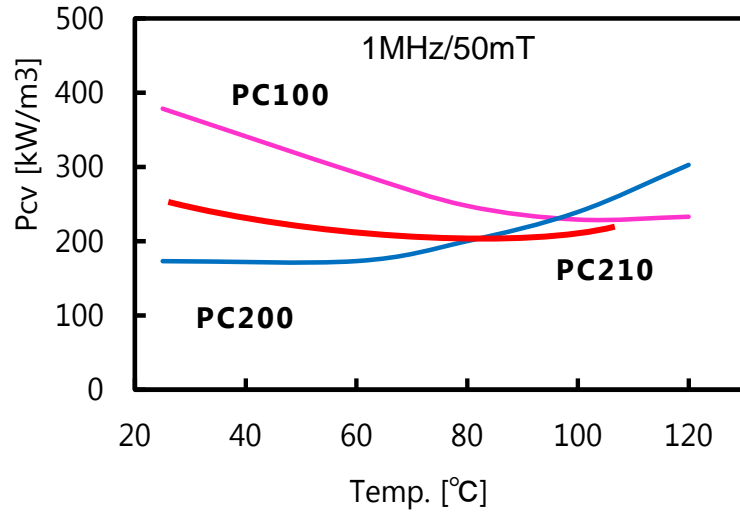
High frequency material road map



Power loss vs temperature curves at 1MHz



- PC200 has lowest Pcv from 1MHz
- flat characteristics of Pcv vs temperature.
- PC200 has min of Pcv at room temperature -> **low stability at high temperature**

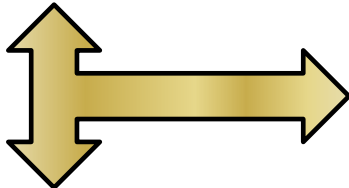
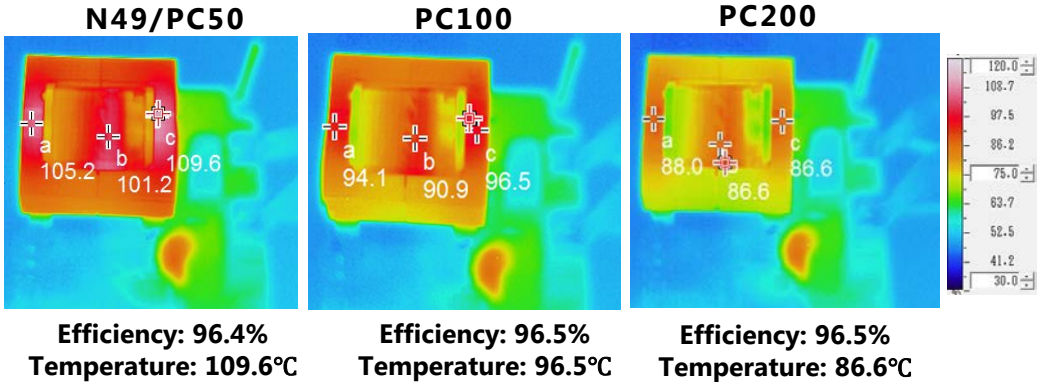


PC100 and PC200 will be unified as PC210.

Evaluation results of PC200

Core Shape
EER42
Po=700W

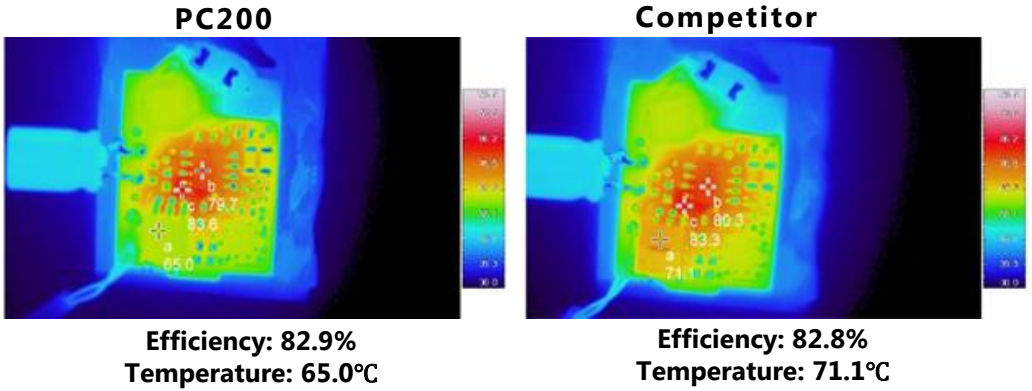
Fsw=1MHz
Vin=380V
Po=700W (Vo=260V)
ΔB=79.6mT(Cal.)



Efficiency is same but surf. temperature is different

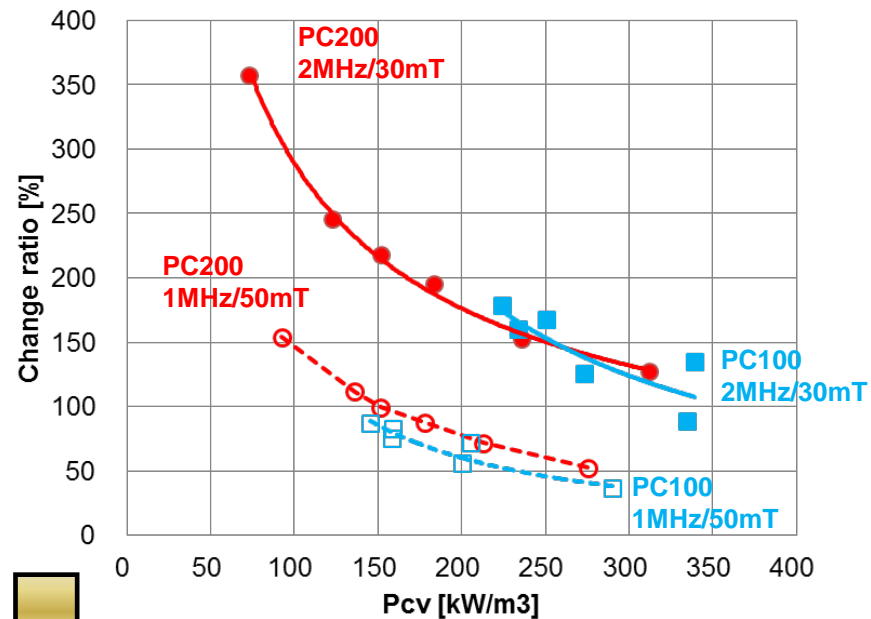
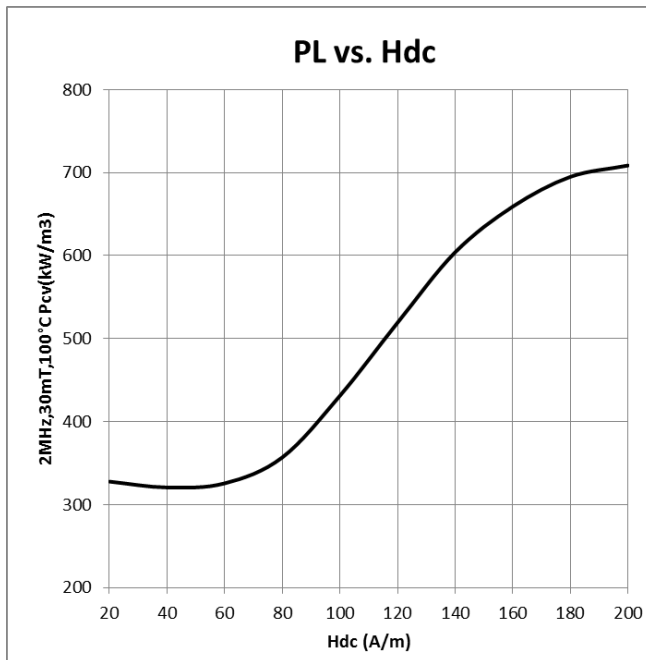
Core Shape
EP6
Po=6W

Fsw=700kHz
Vin=100V
Po=5.77W (Vo=36.4V)
ΔB=150mT(Cal.)



Degradation of power loss under magnetic field

- Under influence of DC magnetic field the power loss increase.
- Heat treatment or demagnetization returns power loss to original state
- The degradation of the power loss **depends on absolute value of Pcv**



Development of PC220 to reduce the Pcv degradation

